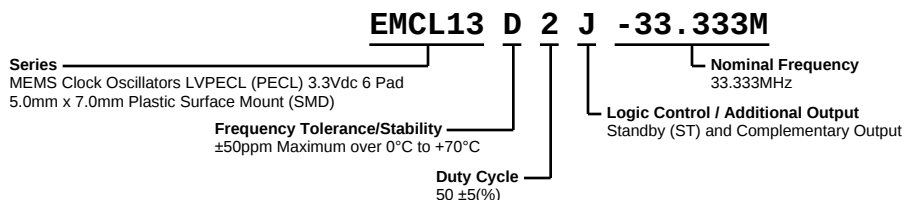


EMCL13D2J-33.333M



ELECTRICAL SPECIFICATIONS

Nominal Frequency	33.333MHz
Frequency Tolerance/Stability	$\pm 50\text{ppm}$ Maximum over 0°C to $+70^{\circ}\text{C}$ (Inclusive of all conditions: Calibration Tolerance at 25°C , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, 1st Year Aging at 25°C , Reflow, Shock, and Vibration)
Aging at 25°C	$\pm 1\text{ppm}$ First Year Maximum
Supply Voltage	$+3.3\text{Vdc} \pm 0.3\text{Vdc}$
Input Current	80mA Maximum (Excluding Load Termination Current)
Output Voltage Logic High (Voh)	2.35Vdc Typical, $V_{cc}-1.025\text{Vdc}$ Minimum
Output Voltage Logic Low (Vol)	1.6Vdc Typical, $V_{cc}-1.62\text{Vdc}$ Maximum
Rise/Fall Time	150pSec Typical, 300pSec Maximum (Measured over 20% to 80% of waveform)
Duty Cycle	$50 \pm 5(\%)$ (Measured at 50% of waveform)
Load Drive Capability	50 Ohms into $V_{cc}-2.0\text{Vdc}$
Output Logic Type	LVPECL
Logic Control / Additional Output	Standby (ST) and Complementary Output
Output Control Input Voltage	Vih of 70% of V_{cc} Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of V_{cc} Maximum to Disable Output and Complementary Output (High Impedance)
Standby Current	30 μA Maximum (ST) Without Load
Period Jitter (Deterministic)	0.2pSec Typical
Period Jitter (Random)	2.0pSec Typical
Period Jitter (RMS)	1.5pSec Typical, 3.0pSec Maximum
Period Jitter (pk-pk)	20pSec Typical, 25pSec Maximum
RMS Phase Jitter (Fj = 637kHz to 10MHz; Random)	1.7pSec Typical
RMS Phase Jitter (Fj = 1MHz to 20MHz; Random)	1.4pSec Typical
RMS Phase Jitter (Fj = 1.875MHz to 20MHz; Random)	1.1pSec Typical
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to $+125^{\circ}\text{C}$

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 2, HBM 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition G, 30,000G
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity Level	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003 (Six I/O Pads on bottom of package only)
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Thermal Shock	MIL-STD-883, Method 1011, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

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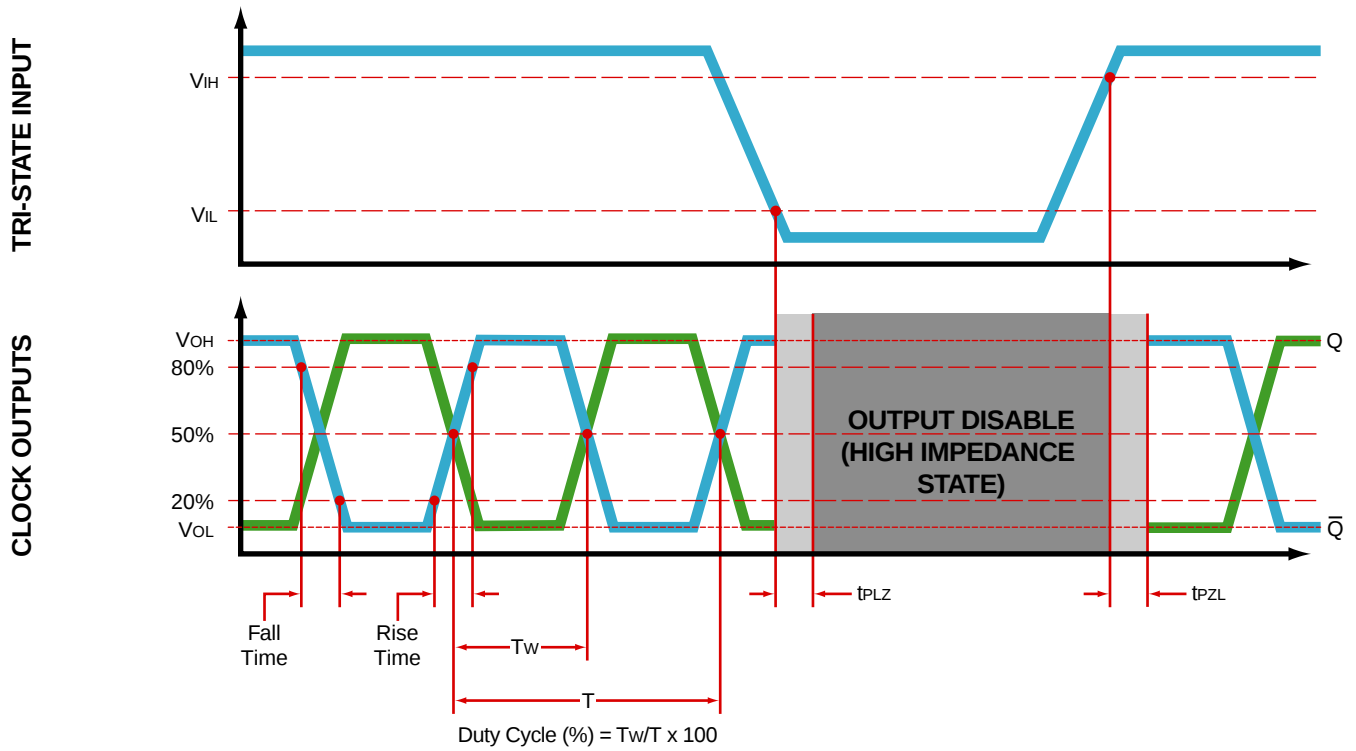
LINE	MARKING
1	XXXX or XXXXX XXXX or XXXXX=Ecliptek Manufacturing Lot Code

Figure 1: Dimensions of the test board. The diagram shows a 3x2 grid of blue square components. Dimensions are given in inches and multiplied by a factor in parentheses. Horizontal dimensions: 1.80 (X6) between columns, 2.39 (X6) from the left edge to the first column. Vertical dimensions: 0.54 (X4) between rows, 2.00 (X6) from the top edge to the first row. A label 'Solder Land (X6)' points to the bottom-right component.

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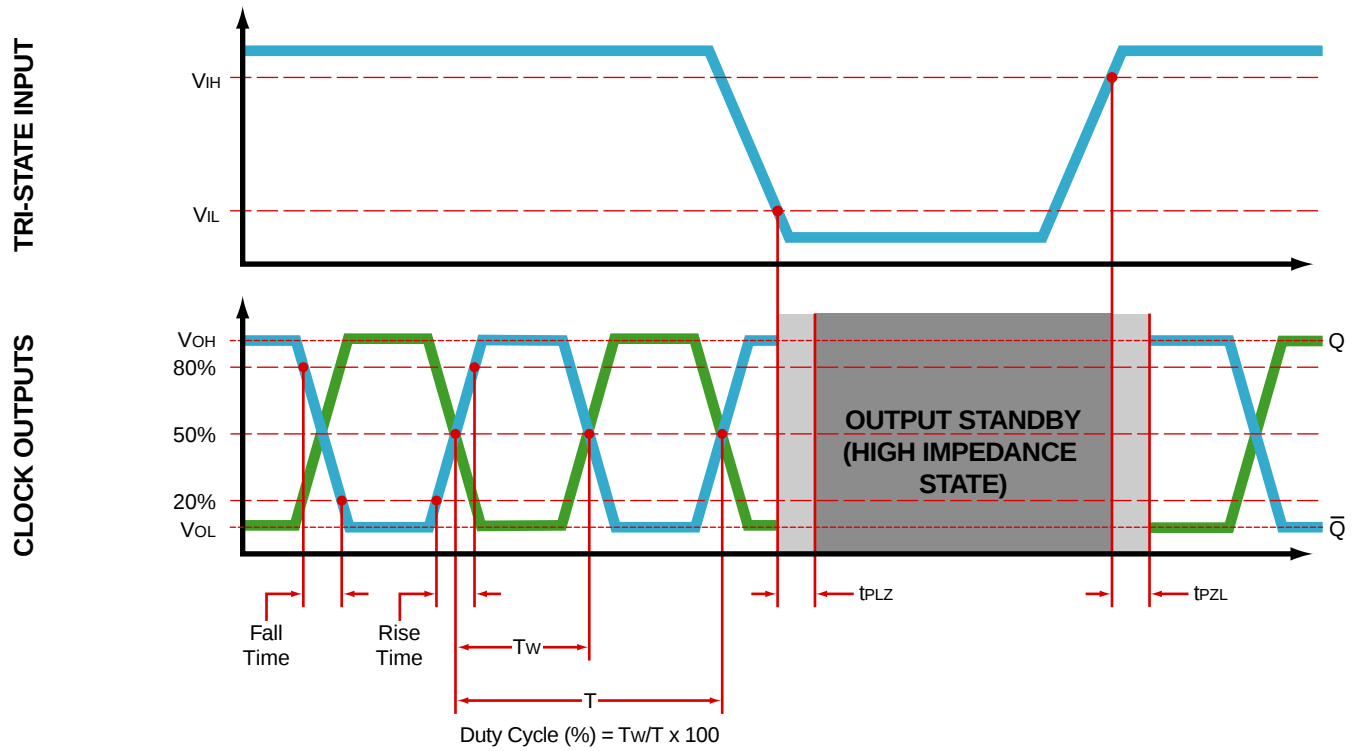
EMCL13D2J-33.333M

OUTPUT WAVEFORM & TIMING DIAGRAM



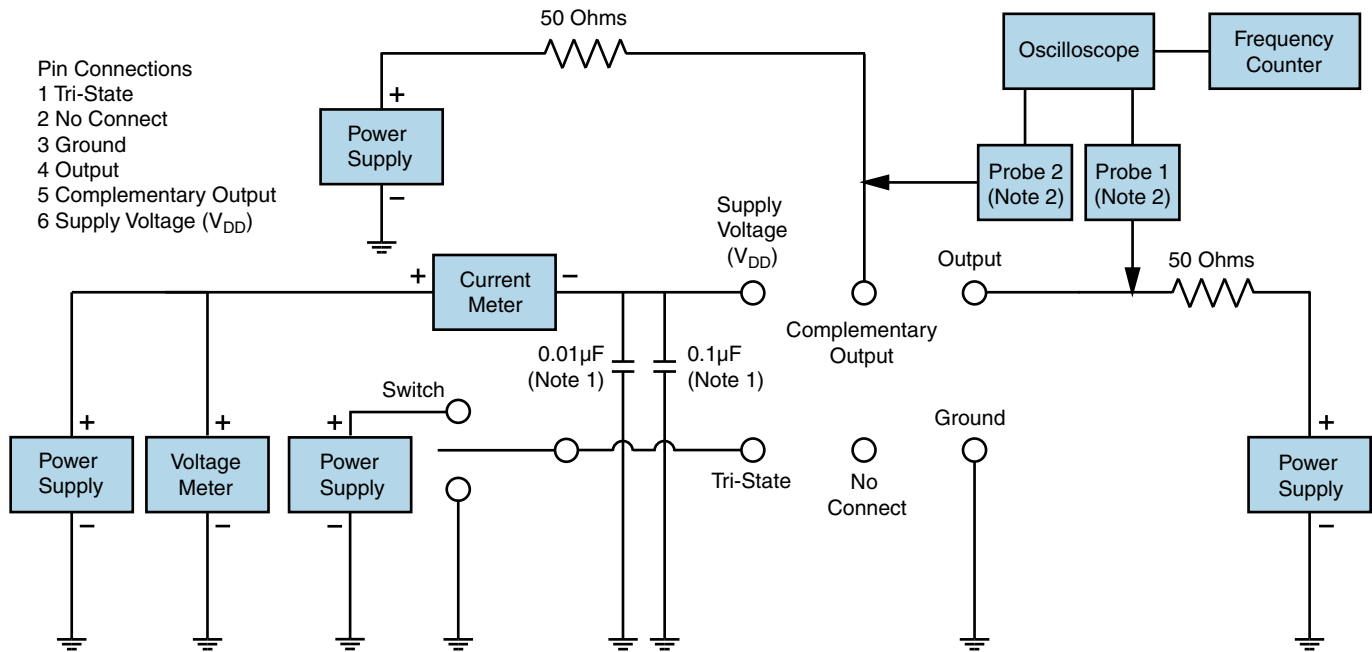
EMCL13D2J-33.333M

OUTPUT WAVEFORM & TIMING DIAGRAM



EMCL13D2J-33.333M

Test Circuit for Tri-State and Complementary Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>500MHz) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

TS MAX to TL (Ramp-up Rate)	3°C/second Maximum
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Preheat

- Temperature Minimum (TS MIN)	150°C
- Temperature Typical (TS TYP)	175°C
- Temperature Maximum (TS MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds

Ramp-up Rate (TL to TP)	3°C/second Maximum
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Time Maintained Above:

- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds

Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (TP Target)	250°C +0/-5°C
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Time within 5°C of actual peak (tp)	20 - 40 seconds
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Ramp-down Rate	6°C/second Maximum
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Time 25°C to Peak Temperature (t)	8 minutes Maximum
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Moisture Sensitivity Level	Level 1
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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

T_S MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_S MIN) N/A
- Temperature Typical (T_S TYP) 150°C
- Temperature Maximum (T_S MAX) N/A
- Time (t_s MIN) 60 - 120 Seconds

Ramp-up Rate (T_L to T_P) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
- Time (t_L) 200 Seconds Maximum

Peak Temperature (T_P) 240°C Maximum

Target Peak Temperature (T_P Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (t_P) 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.